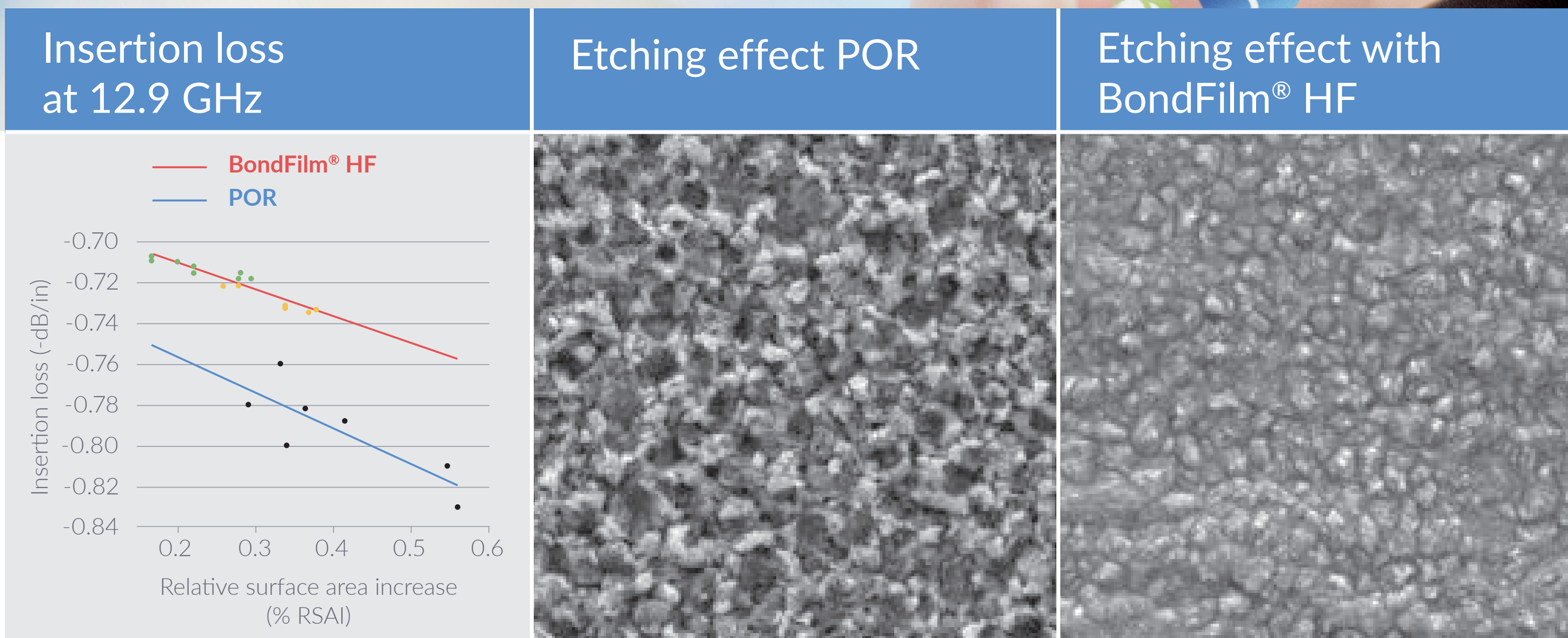


Bonding enhancement solutions
for low signal loss with
high frequency applications



Enhanced performance

For high frequency applications there is a demand for a bonding enhancement process that gives the same excellent thermal reliability of the BondFilm® product range, but with superior performance in terms of reduced signal loss compared with the standard solutions available. BondFilm® HF is a cost effective drop in replacement for conventional bonding enhancement solutions, offering enhanced performance with high frequency applications without the need to revert to more complex NEAP applications.

Features and benefits

- Simple drop in replacement for existing bonding enhancement solutions
- Reduced signal loss fulfils signal Integrity requirements
- Competitive process costs comparable with current bonding systems
- Compatible with a wide range of dielectric materials

BondFilm® HF
Process flow

Acid Clean UC
Sprayable acid cleaner for removal of moderate oxidation (optional)

BondFilm® Cleaner MS
Removes grease, fingerprints, resist residues

BondFilm® Activator MS
For even coverage and no drag-in into main module

BondFilm® HF
Creates uniformly roughened brown organo-metallic coating through intergranular etching